



The European Institute for the PCB Community

Call for papers

EIPC Winter Conference Lyon 2018

“Future trends for successful positioning of Europe’s place in the global supply chain”

EIPC Winter Conference Lyon, France

Date: February 1 & 2, 2018

Bonus Programme: Visit to Alstom, Transport Information Solutions

Presentations on the following topics will be included in the conference programme:

Keynote Topics

Business Outlook: Global Electronics Industry

Future trends in:

- Automotive, Transportation, Space, Avionics
- G5, Medical- Industrial- and other Electronics

Topics Reliability by Application

What Testing is needed and how to MEasure Reliability

How to ensure product Safety and Reliability

Material and finish product Safety and Testing

Topics Tools for Reliability

Responsibility for Product Reliability and Safety

Standards for Product Safety and Reliability

Inhouse process control and conformation Testing

Third party Testing

Topics Design & New Technologies

Success through Evolution- or Disruptive Technologies?

PCBs in Ploymer Technology

Printed Electronics

- Conventional or Inkjet
- 3D Printing

Embedding and 3D application

New technology, Innovations and Invention

- Roadmapping on transportation, Automotive, Train, Avionics

Session The Technology Roadmap for the Electronics Industry

Planes, trains and automobiles

What input is provided through “Roadmap by market segments”

Technology Guidance for managers through Roadmap content

Adapting processes, materials, chemistry, equipments to future technology needs

Strategic Partnership and planning for success through Networking and Roadmap sharing



World Electronic Circuits Council

The EIPC is the European representative at the WECC



Fachverband für Design, Leiterplatten- und Elektronikfertigung

ALSTOM

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